

- Line driver mode supports engine start at a battery voltage as low as 6 V (16 dB and mid-tap voltage $0.25 \times V_P$)
- Programmable clip detect: 2 %, 5 % or 10 %
- Programmable thermal pre-warning
- Pin STB can be programmed/multiplexed with second-clip detect
- Clip information of each channel can be directed separately to pin DIAG or pin STB
- Independent enabling of thermal-, clip- or load fault information (short across the load or to V_P or to ground) on pin DIAG
- Loss-of-ground and open V_P safe (minimum series resistance required)
- All amplifier outputs short-circuit proof to ground, supply voltage and across the load (channel independent)
- All pins short-circuit proof to ground
- Temperature controlled gain reduction to prevent audio holes at high junction temperatures
- Programmable low battery voltage detection to enable 7.5 V or 6 V minimum battery voltage operation
- Overvoltage protection (load-dump safe up to $V_P = 50$ V) with overvoltage pre-warning at 16 V
- Offset detection

3. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{P(\text{oper})}$	operating supply voltage	$R_L = 4 \Omega$	6	14.4	18	V
I_q	quiescent current	no load	-	260	350	mA
		no load; $V_P = 7$ V	-	190	-	mA
P_o	output power	$R_L = 4 \Omega$; $V_P = 14.4$ V; maximum power; $V_i = 2$ V RMS square wave	37	40	-	W
		$R_L = 4 \Omega$; $V_P = 15.2$ V; maximum power; $V_i = 2$ V RMS square wave	41	45	-	W
		$R_L = 4 \Omega$; $V_P = 14.4$ V; THD = 0.5 %	18	20	-	W
		$R_L = 4 \Omega$; $V_P = 14.4$ V; THD = 10 %	23	25	-	W
		$R_L = 2 \Omega$; $V_P = 14.4$ V; THD = 10 %	40	44	-	W
		$R_L = 2 \Omega$; $V_P = 14.4$ V; maximum power; $V_i = 2$ V RMS square wave	58	64	-	W
THD	total harmonic distortion	$P_o = 1$ W to 12 W; $f_i = 1$ kHz; $R_L = 4 \Omega$; BTL mode	-	0.01	0.1	%
		$P_o = 4$ W; $f_i = 1$ kHz; $R_L = 4 \Omega$; best efficiency mode	-	0.03	-	%
$V_{n(o)}$	output noise voltage	filter 20 Hz to 22 kHz; $R_S = 1$ k Ω				
		amplifier mode	-	43	65	μ V
		line driver mode	-	25	33	μ V

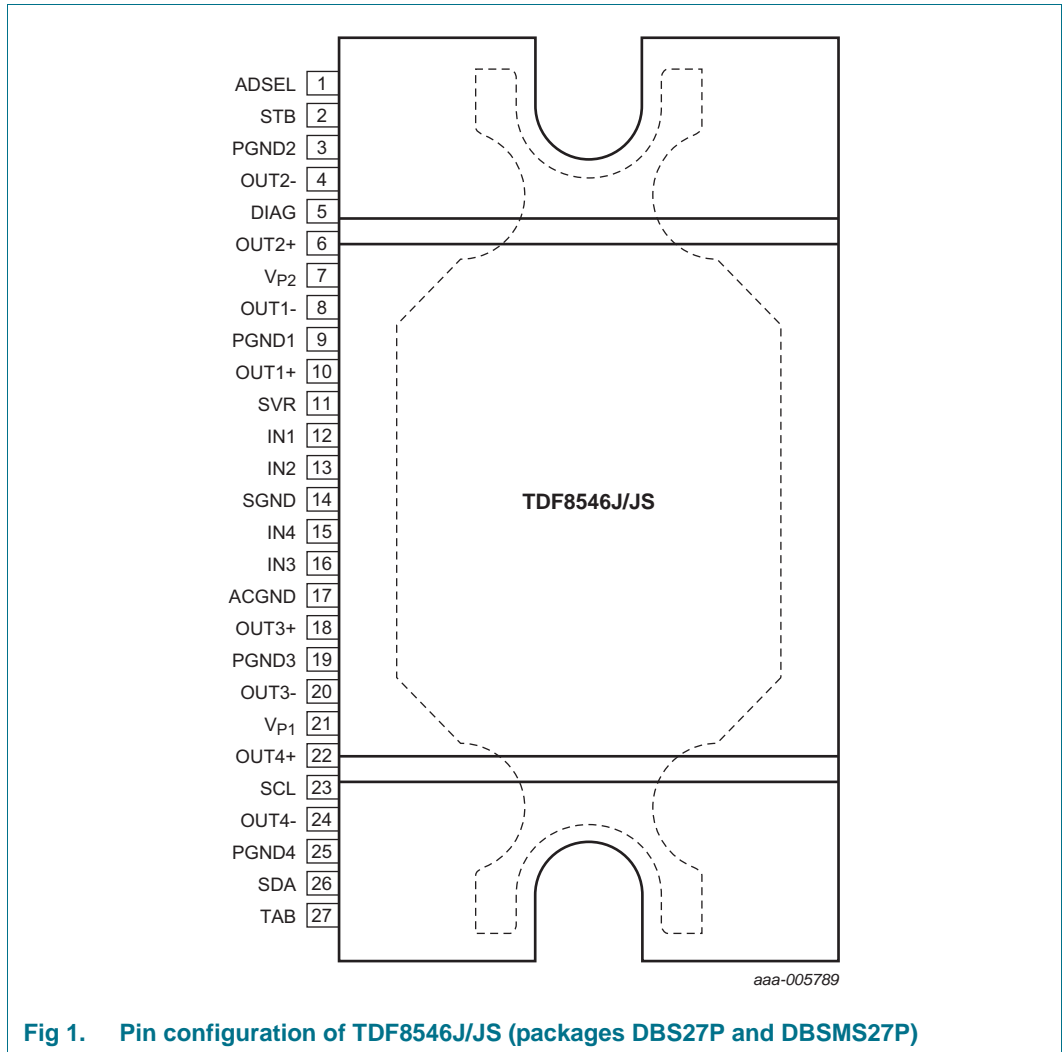
4. Ordering information

Table 2. Ordering information

Type number	Package		
	Name	Description	Version
TDF8546J	DBS27P	plastic DIL-bent-SIL (special bent) power package; 27 leads (lead length 6.8 mm)	SOT827-1
TDF8546TH	HSOP36	plastic, heatsink small outline package; 36 leads; low stand-off height	SOT851-1
TDF8546JS	DBSMS27P	plastic dual bent surface mounted SIL power package; 27 leads	SOT1154-1

5. Pinning information

5.1 Pinning



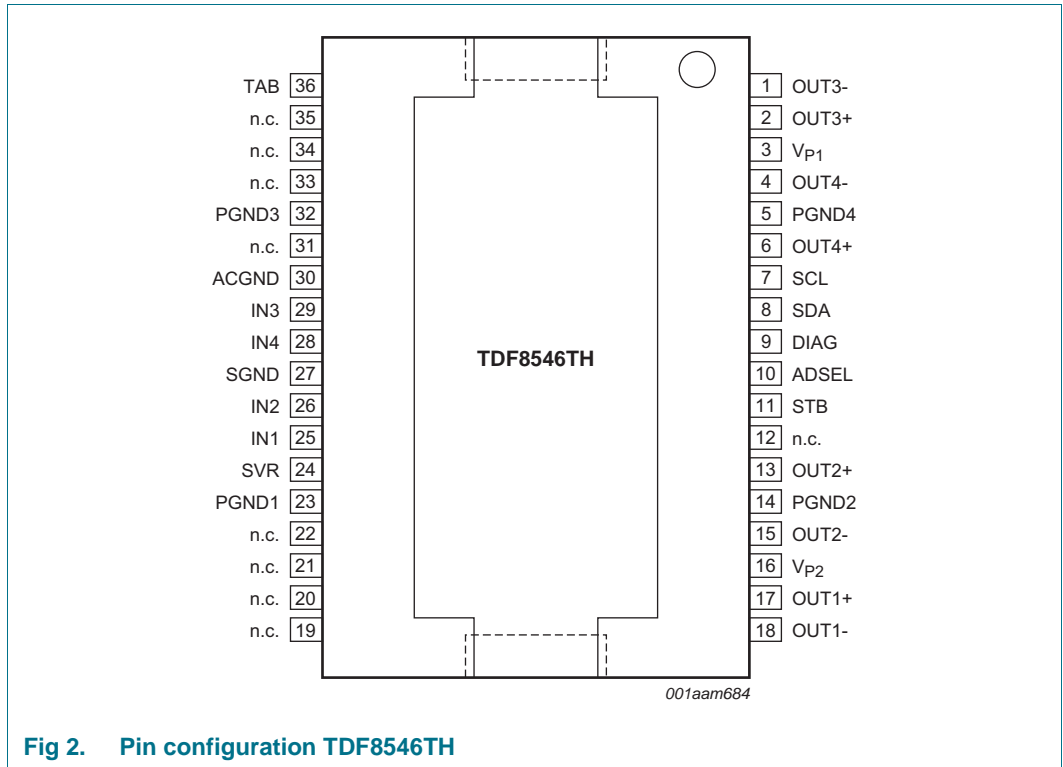


Fig 2. Pin configuration TDF8546TH

5.2 Pin description

Table 3. Pin description

Symbol	Pin		Description
	TDF8546J/JS	TDF8546TH	
ADSEL	1	10	I ² C-bus address select
STB	2	11	Standby (I ² C-bus mode) or mode pin (legacy mode) programmable second clip indicator
PGND2	3	14	channel 2 power ground
OUT2-	4	15	channel 2 negative output (right rear)
DIAG	5	9	diagnostic and clip detection output
OUT2+	6	13	channel 2 positive output (right rear)
V _{P2}	7	16	power supply voltage 2
OUT1-	8	18	channel 1 negative output (right front)
PGND1	9	23	channel 1 power ground
OUT1+	10	17	channel 1 positive output (right front)
SVR	11	24	half supply voltage filter capacitor
IN1	12	25	channel 1 input
IN2	13	26	channel 2 input
SGND	14	27	signal ground
IN4	15	28	channel 4 input
IN3	16	29	channel 3 input
ACGND	17	30	AC ground
OUT3+	18	2	channel 3 positive output (left front)
PGND3	19	32	channel 3 power ground
OUT3-	20	1	channel 3 negative output (left front)
V _{P1}	21	3	power supply voltage 1
OUT4+	22	6	channel 4 positive output (left rear)
SCL	23	7	I ² C-bus clock input
OUT4-	24	4	channel 4 negative output (left rear)
PGND4	25	5	channel 4 power ground
SDA	26	8	I ² C-bus data input and output
TAB	27	36	heatsink connection; must be connected to ground
n.c.	-	12, 19, 20, 21, 22, 31, 33, 34, 35	not connected

6. Thermal characteristics

Table 4. Thermal characteristics

Symbol	Parameter	Conditions	Typ	Unit
DBS27/DBSMS27P				
$R_{th(j-c)}$	thermal resistance from junction to case		1	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient		40	K/W
HSOP36				
$R_{th(j-c)}$	thermal resistance from junction to case		1	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient		35	K/W

7. Characteristics

Table 5. Characteristics

$T_{amb} = 25\text{ °C}$; $V_P = 14.4\text{ V}$; unless otherwise specified. Tested at $T_{amb} = 25\text{ °C}$; guaranteed for $T_j = -40\text{ °C}$ to $+150\text{ °C}$; functionality is guaranteed for $V_P < 10\text{ V}$ unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Supply voltage behavior						
$V_{P(oper)}$	operating supply voltage	$R_L = 4\ \Omega$	6	14.4	18	V
		$R_L = 2\ \Omega$	6	14.4	16	V
I_q	quiescent current	no load	-	260	350	mA
		no load; $V_P = 7\text{ V}$	-	190	-	mA
I_{off}	off-state current	$V_{STB} = 0.4\text{ V}$	-	4	10	μA
V_O	output voltage	DC				
		amplifier on; high gain/low gain mode	6.6	7.1	7.6	V
		line driver mode; IB4[D2] = 0; IB3[D5:D6] = 1	3.0	3.4	3.8	V
$V_{P(low)(mute)}$	low supply voltage mute	rising supply voltage				
		IB4[D0] = 1	7.0	7.7	8.1	V
		IB4[D0] = 0	5.4	5.7	6.2	V
		falling supply voltage				
		IB4[D0] = 1	6.5	7.2	7.7	V
$\Delta V_{P(low)(mute)}$	low supply voltage mute hysteresis	IB4[D0] = 1	0.1	0.5	0.8	V
		IB4[D0] = 0	0.1	0.3	0.7	V
$V_{P(ovp)pwarn}$	pre-warning overvoltage protection supply voltage	rising supply voltage	15.2	16	16.9	V
		falling supply voltage	14.4	15.2	16.2	V
		hysteresis	-	0.8	-	V
$V_{th(ovp)}$	overvoltage protection threshold voltage	rising supply voltage	18	20	22	V
V_{POR}	power-on reset voltage	falling supply voltage	-	3.1	4.5	V
$V_{O(offset)}$	output offset voltage	amplifier on	-75	0	+75	mV
		amplifier mute	-25	0	+25	mV
		line driver mode	-45	0	+45	mV

Table 5. Characteristics ...continued

$T_{amb} = 25\text{ °C}$; $V_P = 14.4\text{ V}$; unless otherwise specified. Tested at $T_{amb} = 25\text{ °C}$; guaranteed for $T_j = -40\text{ °C}$ to $+150\text{ °C}$; functionality is guaranteed for $V_P < 10\text{ V}$ unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Mode select and second clip detection: pin STB						
V_{STB}	voltage on pin STB	off-by mode selected				
		I ² C-bus mode	-	-	0.8	V
		legacy mode (I ² C-bus mode off)	-	-	0.8	V
		mute selected				
		legacy mode (I ² C-bus mode off)	2.5	-	4.5	V
		operating mode selected				
		I ² C-bus mode	2.5	-	V_P	V
		legacy mode (I ² C-bus mode off)	5.9	-	V_P	V
		low voltage on pin STB when pulled LOW during clipping; clip detection on STB active	[1]			
$I_{STB} = 150\text{ }\mu\text{A}$	5.6	5.9	6.5	V		
$I_{STB} = 500\text{ }\mu\text{A}$	6.1	-	7.4	V		
I_{STB}	current on pin STB	$0\text{ V} < V_{STB} < 8.5\text{ V}$; clip detection not active	[1]	-	5	30 μA
Start-up/shut-down/mute timing						
t_{wake}	wake-up time	time after wake-up via pin STB before first I ² C-bus transmission is recognized;	-	300	500	μs
$I_{LO(SVR)}$	output leakage current on pin SVR		-	-	5	μA
$t_{d(mute_off)}$	mute off delay time	time from amplifier start to 10 % of output signal; $I_{LO} = 0\text{ }\mu\text{A}$	[2]			
		I ² C-bus mode; with $I_{LO} = 5\text{ }\mu\text{A} \rightarrow +15\text{ ms}$; no DC-load ($I_{B1}[D1] = 0$);	-	430	650	ms
		legacy mode; with $I_{LO} = 5\text{ }\mu\text{A} \rightarrow +20\text{ ms}$; $V_{STB} = 7\text{ V}$; $R_{ADSEL} = 0\text{ }\Omega$;	-	430	650	ms
t_{amp_on}	amplifier on time	time from amplifier start to amplifier on; 90 % of output signal; $I_{LO} = 0\text{ }\mu\text{A}$	[2]			
		I ² C-bus mode; with $I_{LO} = 5\text{ }\mu\text{A} \rightarrow +30\text{ ms}$; no DC-load ($I_{B1}[D1] = 0$);	-	550	800	ms
		legacy mode; with $I_{LO} = 5\text{ }\mu\text{A} \rightarrow +20\text{ ms}$; $V_{STB} = 7\text{ V}$; $R_{ADSEL} = 0\text{ }\Omega$;	-	550	800	ms

Table 5. Characteristics ...continued

$T_{amb} = 25\text{ °C}$; $V_P = 14.4\text{ V}$; unless otherwise specified. Tested at $T_{amb} = 25\text{ °C}$; guaranteed for $T_j = -40\text{ °C}$ to $+150\text{ °C}$; functionality is guaranteed for $V_P < 10\text{ V}$ unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
t_{off}	amplifier switch-off time	time to DC output voltage $< 0.1\text{ V}$; [2] $I_{LO} = 0\text{ }\mu\text{A}$				
		I ² C-bus mode; with $I_{LO} = 5\text{ }\mu\text{A} \rightarrow +0\text{ ms}$;	250	500	750	ms
		via pin STB; (IB4[D6] = 0); with $I_{LO} = 5\text{ }\mu\text{A} \rightarrow +0\text{ ms}$;	250	500	750	ms
$t_{d(mute-on)}$	delay time from mute to on	from 10 % to 90 % of output signal; $V_i = 50\text{ mV}$; I ² C-bus mode (IB2[D1, D2] = 1 to 0) or IB2(D0 = 1 to 0) or legacy mode ($V_{STB} = 3\text{ V}$ to 7 V);	5	15	40	ms
$t_{d(soft_mute)}$	soft mute delay time	from 90 % to 10 % of output signal; $V_i = 50\text{ mV}$; I ² C-bus mode (IB2[D1, D2] = 0 to 1) or legacy mode ($V_{STB} = 7\text{ V}$ to 3 V);	5	15	40	ms
$t_{d(fast_mute)}$	fast mute delay time	from 90 % to 10 % of output signal; $V_i = 50\text{ mV}$; I ² C-bus mode (IB2[D0] = 0 to 1, or V_{STB} from $> 5.9\text{ V}$ to $< 0.8\text{ V}$ in $1\text{ }\mu\text{s}$;	-	0.4	1	ms
$t_{(start-Vo(off))}$	engine start to output off time	V_P from 14.4 V to 5 V in 1.5 ms ; $V_o < 0.5\text{ V}$;	-	0.1	1	ms
$t_{(start-SVRoff)}$	engine start to SVR off time	V_P from 14.4 V to 5 V in 1.5 ms ; $V_{SVR} < 0.7\text{ V}$;	-	40	75	ms
I²C-bus interface [3]						
V_{IL}	LOW-level input voltage	pins SCL and SDA	-	-	1.5	V
V_{IH}	HIGH-level input voltage	pins SCL and SDA	2.3		5.5	V
V_{OL}	LOW-level output voltage	pin SDA; $I_L = 5\text{ mA}$	-	-	0.4	V
f_{SCL}	SCL clock frequency		-	400	-	kHz
V_{ADSEL}	voltage on pin ADSEL	I ² C-bus address $A[6:0] = 1101\ 101$				
		$R_{seriesADSEL} = 0\text{ }\Omega$	4	5	11	V
		$R_{seriesADSEL} = 100\text{ k}\Omega$	-	-	V_P	V
$I_{I(ADSEL)}$	input current on pin ADSEL	$V_{STB} = 5\text{ V}$; $V_{ADSEL} = 5\text{ V}$	-	2	10	μA
R_{ADSEL}	resistance on pin ADSEL	I ² C-bus address $A[6:0] = 1101\ 110$	99	100	101	$\text{k}\Omega$
		I ² C-bus address $A[6:0] = 1101\ 111$	29.7	30	30.3	$\text{k}\Omega$
		I ² C-bus address $A[6:0] = 1101\ 010$	9.9	10	10.1	$\text{k}\Omega$
		legacy mode	-	-	0.47	$\text{k}\Omega$
$V_{P(latch)}$	latch supply voltage	does not react to address selection changes	-	-	6	V

Start-up diagnostics

Table 5. Characteristics ...continued

$T_{amb} = 25\text{ °C}$; $V_P = 14.4\text{ V}$; unless otherwise specified. Tested at $T_{amb} = 25\text{ °C}$; guaranteed for $T_j = -40\text{ °C}$ to $+150\text{ °C}$; functionality is guaranteed for $V_P < 10\text{ V}$ unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
t_{sudiag}	start-up diagnostic time	from start-up diagnostic command via I ² C-bus until completion of start-up diagnostic; $V_O + < 0.1\text{ V}$; $V_O - < 0.1\text{ V}$ (no load) IB1[D1] = 1;	50	130	250	ms
$t_{d(sudiag-on)}$	start-up diagnostic to on delay time	at 90 % of output signal; IB1[D0:D1] = 11;	-	680	-	ms
V_{offset}	offset voltage	start-up diagnostic offset voltage under no load condition	1.3	2	2.5	V
$R_{Ldet(sudiag)}$	start-up diagnostic load detection resistance	shorted load				
		high gain; IB3[D6:D5] = 00	-	-	0.5	Ω
		low gain; IB3[D6:D5] = 11	-	-	1.5	Ω
		normal load				
		high gain (IB3[D6:D5] = 00)	1.5	-	20	Ω
		low gain (IB3[D6:D5] = 11)	3.2	-	20	Ω
		line driver load	80	-	200	Ω
		open load	400	-	-	Ω

Amplifier diagnostics

$V_{OL(DIAG)}$	LOW-level output voltage on pin DIAG	fault condition; $I_{DIAG} = 1\text{ mA}$	-	-	0.3	V
$V_{O(offset_det)}$	output voltage at offset detection		±1.0	±1.3	±2.0	V
THD_{clip}	total harmonic distortion clip detection level	$V_P > 10\text{ V}$				
		IB2[D7:D6] = 10	-	10	-	%
		IB2[D7:D6] = 01	-	5	-	%
		IB2[D7:D6] = 00	-	2	-	%
$T_{j(AV)(pwarn)}$	pre-warning average junction temperature	IB3[D4] = 0 or legacy mode	150	160	170	°C
		IB3[D4] = 1	125	135	145	°C
$T_{j(AV)(G(-0.5dB))}$	average junction temperature for 0.5 dB gain reduction	$V_i = 0.05\text{ V}$; best efficiency mode turns off when activated	-	175	-	°C
$\Delta G_{(th_fold)}$	gain reduction of thermal foldback	when all channels switch off	-	20	-	dB
I_o	output current	I ² C-bus mode; IB5[D7] = 0; AC load bit set; peak current				
		IB4[D1] = 1	500	-	-	mA
		IB4[D1] = 0	275	-	-	mA
		I ² C-bus mode; IB5[D7] = 0; AC load bit not set; peak current				
		IB4[D1] = 1	-	-	250	mA
		IB4[D1] = 0	-	-	100	mA

Table 5. Characteristics ...continued

$T_{amb} = 25\text{ °C}$; $V_P = 14.4\text{ V}$; unless otherwise specified. Tested at $T_{amb} = 25\text{ °C}$; guaranteed for $T_j = -40\text{ °C}$ to $+150\text{ °C}$; functionality is guaranteed for $V_P < 10\text{ V}$ unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit	
Amplifier							
P_o	output power	$R_L = 4\ \Omega$; $V_P = 14.4\text{ V}$; THD = 0.5 %	18	20	-	W	
		$R_L = 4\ \Omega$; $V_P = 14.4\text{ V}$; THD = 10 %	23	25	-	W	
		$R_L = 2\ \Omega$; $V_P = 14.4\text{ V}$; THD = 0.5 %	29	32	-	W	
		$R_L = 2\ \Omega$; $V_P = 14.4\text{ V}$; THD = 10 %	40	44	-	W	
$P_{o(max)}$	maximum output power	$R_L = 4\ \Omega$; $V_P = 14.4\text{ V}$; $V_i = 2\text{ V RMS square wave}$	37	40	-	W	
		$R_L = 4\ \Omega$; $V_P = 15.2\text{ V}$; $V_i = 2\text{ V RMS square wave}$	41	45	-	W	
		$R_L = 2\ \Omega$; $V_P = 14.4\text{ V}$; $V_i = 2\text{ V RMS square wave}$	58	64	-	W	
THD	total harmonic distortion	$P_o = 1\text{ W to }12\text{ W}$; $f_i = 1\text{ kHz}$; $R_L = 4\ \Omega$; BTL mode	-	0.01	0.1	%	
		$P_o = 1\text{ W}$; $f_i = 1\text{ kHz}$; $R_L = 4\ \Omega$; $V_P = 7\text{ V}$; BTL and best efficiency mode	-	0.01	0.1	%	
		$P_o = 4\text{ W}$; $f_i = 1\text{ kHz}$; $R_L = 4\ \Omega$; best efficiency mode	-	0.03	0.1	%	
		$P_o = 1\text{ W to }12\text{ W}$; $f_i = 20\text{ kHz}$; $R_L = 4\ \Omega$; best efficiency mode	-	0.3	0.4	%	
		$V_o = 1\text{ V (RMS)}$ and 4 V (RMS) , $f_i = 1\text{ kHz}$; line driver mode	-	0.02	0.05	%	
		$P_o = 1\text{ W to }12\text{ W}$; $f_i = 1\text{ kHz}$; $R_L = 4\ \Omega$; low gain mode	-	0.01	0.1	%	
α_{cs}	channel separation	best efficiency mode; $R_S = 1\text{ k}\Omega$; $R_{ACGND} = 250\ \Omega$	[4]				
		$f_i = 1\text{ kHz}$	65	80	-	dB	
		$f_i = 10\text{ kHz}$	55	65	-	dB	
SVRR	supply voltage ripple rejection	$f_i = 1\text{ kHz}$; $R_S = 1\text{ k}\Omega$; $R_{ACGND} = 250\ \Omega$; best efficiency mode; tested at $V_P = 10.5\text{ V}$	[4]	55	70	-	dB
CMRR	common mode rejection ratio	amplifier mode; $V_{cm} = 0.3\text{ V (p-p)}$; $f_i = 1\text{ kHz to }3\text{ kHz}$, $R_S = 1\text{ k}\Omega$; $R_{ACGND} = 250\ \Omega$; best efficiency mode	[4]				
		common mode input to differential output ($V_{O(dif)}$ / $V_{I(cm)}$) + 26 dB)	55	65	-	dB	
		common mode input to common mode output ($V_{O(cm)}$ / $V_{I(cm)}$) + 26 dB)	50	58	-	dB	

Table 5. Characteristics ...continued

$T_{amb} = 25\text{ °C}$; $V_P = 14.4\text{ V}$; unless otherwise specified. Tested at $T_{amb} = 25\text{ °C}$; guaranteed for $T_j = -40\text{ °C}$ to $+150\text{ °C}$; functionality is guaranteed for $V_P < 10\text{ V}$ unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
ΔV_o	output voltage variation	plop during switch-on and switch-off; best efficiency mode	[5]			
		from off to mute and mute to off	-	-	7.5	mV
		from mute to on and on to mute (soft mute)	-	-	7.5	mV
		from off to on and on to off (start-up diagnostic enabled)	-	-	7.5	mV
$V_{n(o)}$	output noise voltage	filter 20 Hz to 22 kHz (6 th order); $R_S = 1\text{ k}\Omega$				
		mute mode	-	15	23	μV
		line driver mode	-	25	33	μV
		amplifier mode; best efficiency mode	-	43	65	μV
		amplifier mode; best efficiency mode; $R_S = 50\ \Omega$	-	40	60	μV
$G_{v(\text{amp})}$	voltage gain amplifier mode	single-ended in to differential out; best efficiency mode	25.5	26	26.5	dB
$G_{v(\text{ld})}$	voltage gain line driver mode	single-ended in to differential out; best efficiency mode	15.5	16	16.5	dB
Z_i	input impedance	$T_{amb} = -40\text{ °C}$ to $+105\text{ °C}$	38	62	105	$\text{k}\Omega$
		$T_{amb} = 0\text{ °C}$ to 105 °C	55	62	105	$\text{k}\Omega$
α_{mute}	mute attenuation	$V_{o(\text{on})} / V_{o(\text{mute})}$; $V_i = 50\text{ mV}$	80	92	-	dB
$V_{o(\text{mute})(\text{RMS})}$	RMS mute output voltage	$V_i = 1\text{ V RMS}$; filter 20 Hz to 22 kHz	-	16	29	μV
B_p	power bandwidth	-1 dB	-	20 to 20000	-	Hz
$C_{L(\text{crit})}$	critical load capacitance	no oscillation; R_L between $2\ \Omega$ and open load; C_L from all outputs to GND	22	-	-	nF

Best efficiency mode control

$V_{o(\text{swoff})\text{be}}$	best efficiency switch-off output voltage	best efficiency switch open				
		4 Ω load selected; IB5[D4] = 1	-	0.9	-	V
		2 Ω load selected; IB5[D4] = 0	-	1.7	-	V
$R_{\text{sw}(\text{be})}$	best efficiency switch resistance		-	1.0	-	Ω

- [1] V_{STB} depends on the current into pin STB: minimum = $(1429\ \Omega \times I_{\text{STB}}) + 5.4\text{ V}$, maximum = $(3143\ \Omega \times I_{\text{STB}}) + 5.6\text{ V}$.
- [2] The times are specified without leakage current. For a leakage current of $5\ \mu\text{A}$ on pin SVR, the delta time is specified. If the capacitor value on pin SVR changes $\pm 30\%$, the specified time also changes $\pm 30\%$. The specified times include an ESR of $15\ \Omega$ for the capacitor on pin SVR.
- [3] Standard I²C-bus specification: maximum LOW-level = $0.3V_{\text{DD}}$, minimum HIGH-level = $0.7V_{\text{DD}}$. To comply with 5 V and 3.3 V logic, $V_{\text{DD}} = 5\text{ V}$ defines the maximum LOW-level and $V_{\text{DD}} = 3.3\text{ V}$ defines the minimum HIGH-level.
- [4] For optimum channel separation (α_{cs}), supply voltage ripple rejection (SVRR) and common mode rejection ratio (CMRR), a resistor $R_{\text{ACGND}} = \frac{R_S}{4}\ \Omega$ must be in series with the ACGND capacitor.
- [5] The plop-noise during amplifier switch-on and switch-off is measured using an ITU-R 2 k filter; see [Figure 4](#).

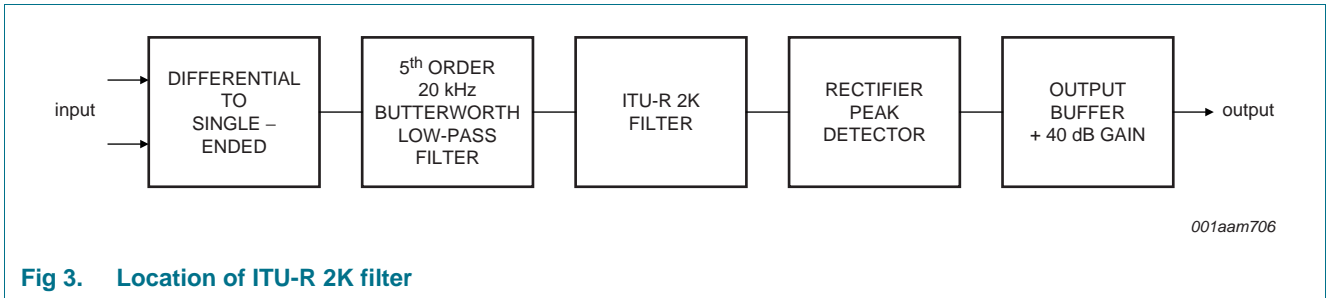
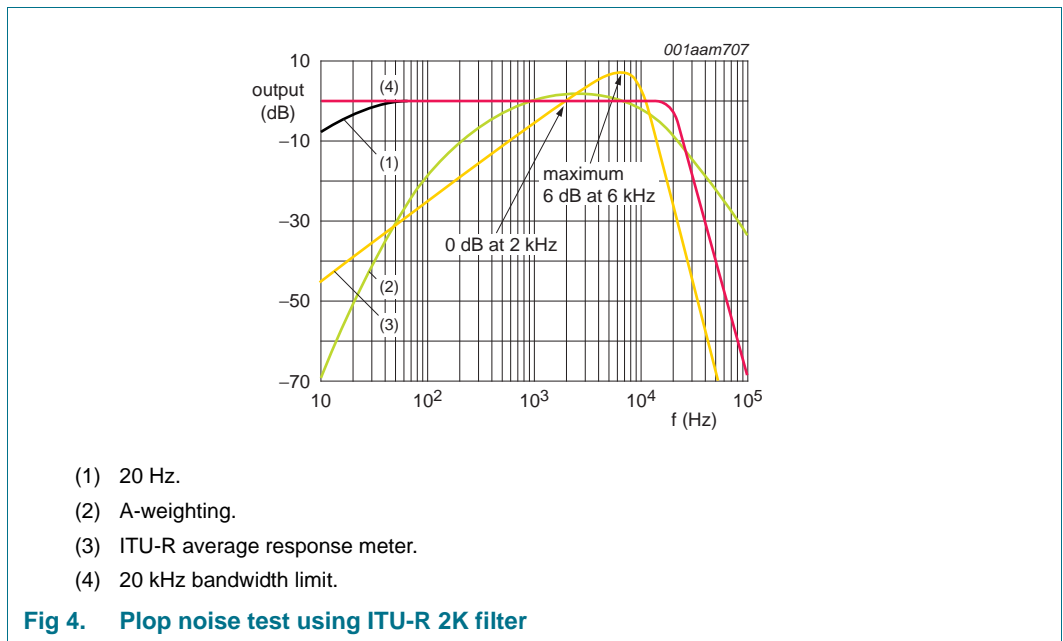


Fig 3. Location of ITU-R 2K filter



8. Package outline

DBS27P: plastic DIL-bent-SIL (special bent) power package; 27 leads (lead length 6.8 mm)

SOT827-1

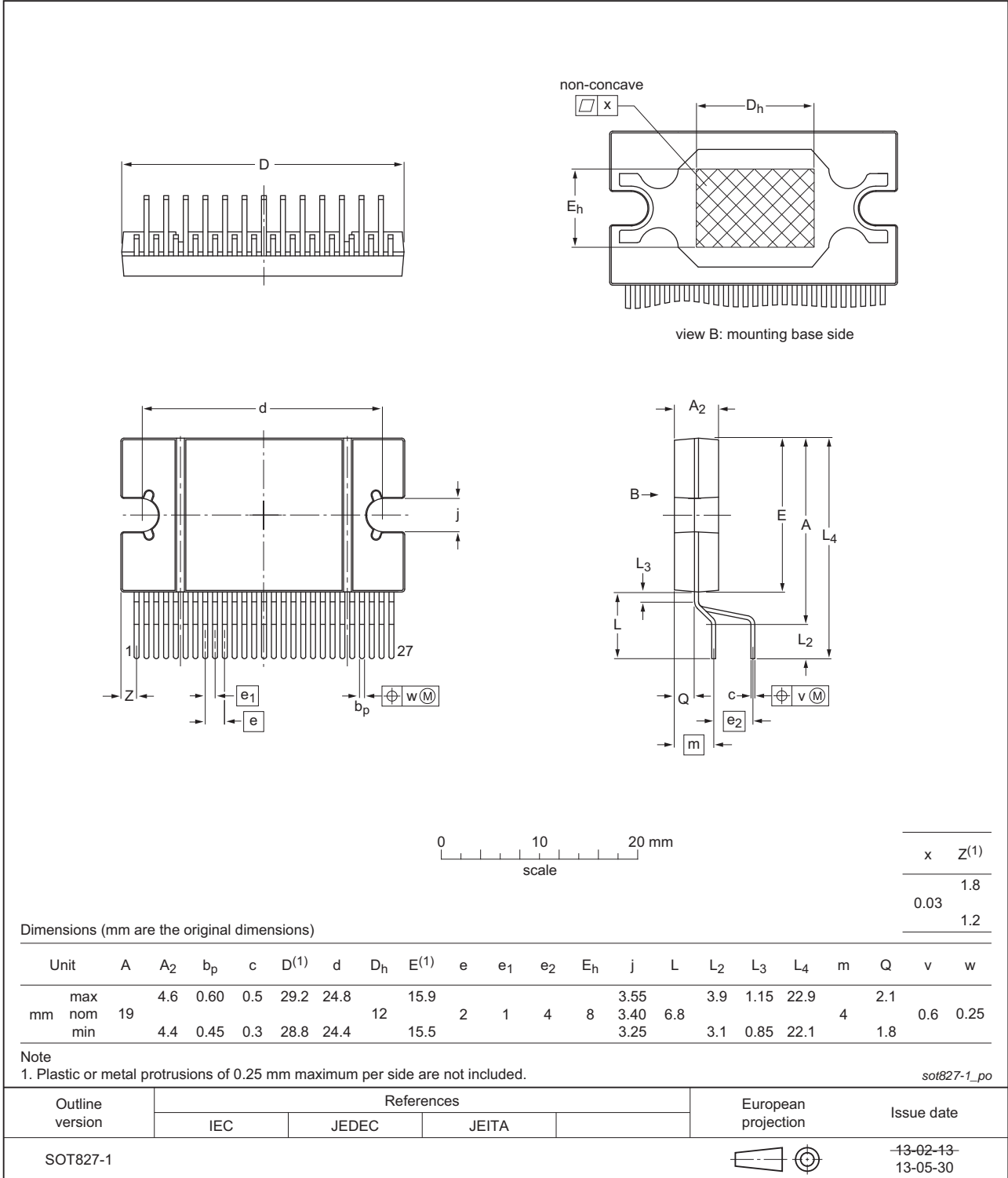


Fig 5. Package outline SOT827-1 (DBS27P)

HSOP36: plastic, heatsink small outline package; 36 leads; low stand-off height

SOT851-1

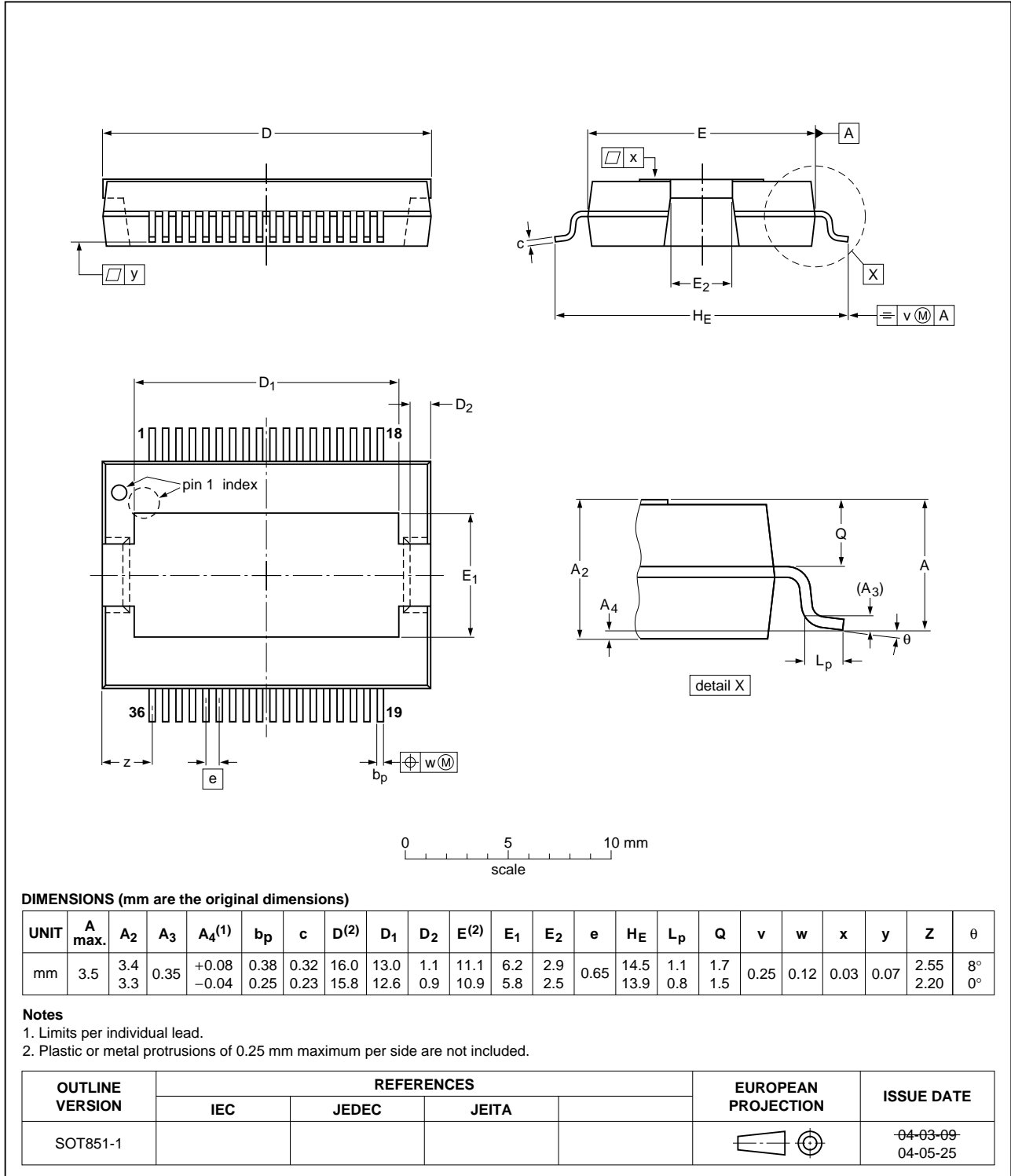


Fig 6. Package outline SOT851-1 (HSOP36)

DBSMS27P: plastic dual bent surface mounted SIL power package; 27 leads

SOT1154-1

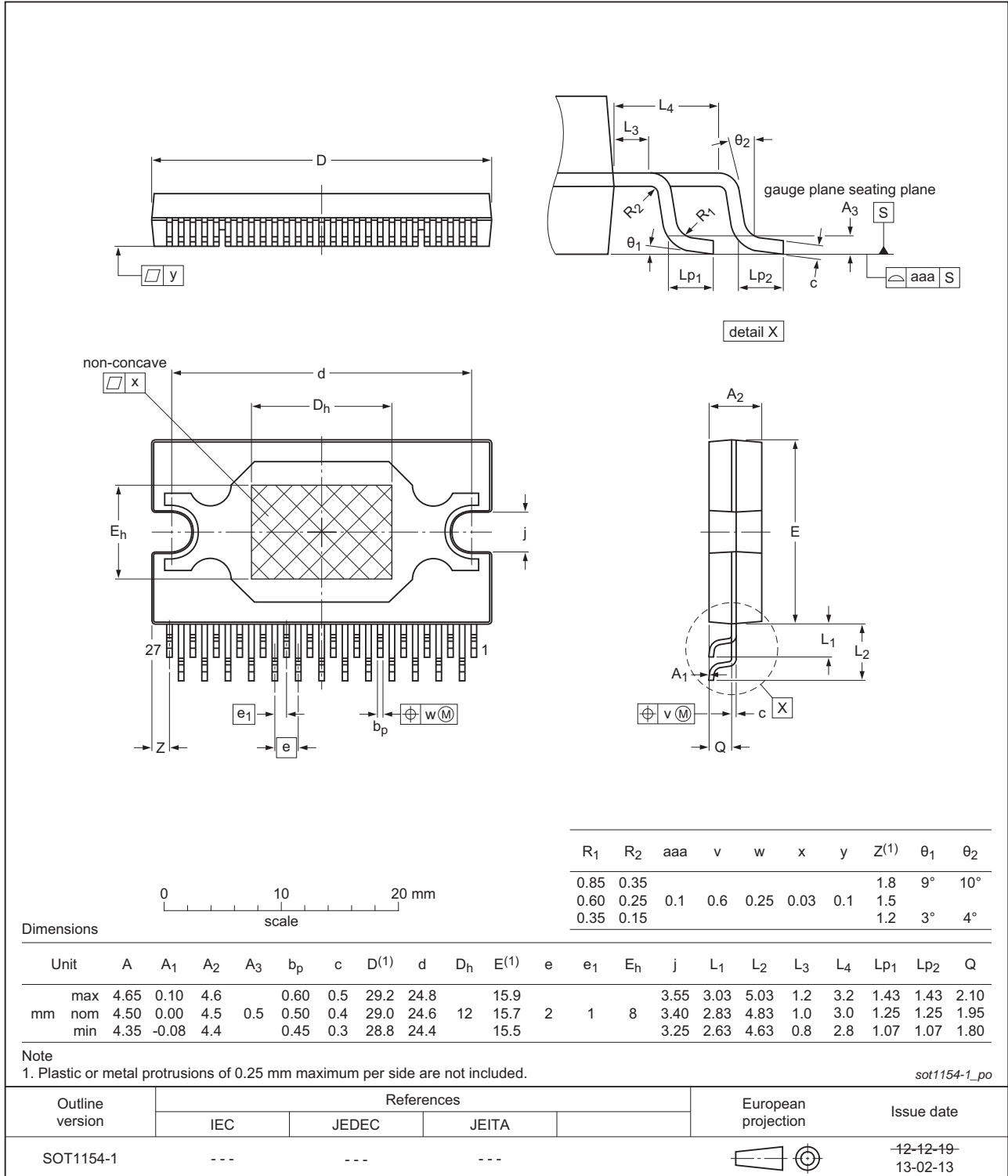


Fig 7. Package outline SOT1154-1 (DBSMS27P)

9. Revision history

Table 6. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
TDF8546 v.8	20130927	Product short data sheet	-	-

10. Legal information

10.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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[2] The term 'short data sheet' is explained in section "Definitions".

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